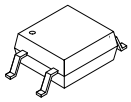
5-Pin Mini Flat Package High Speed Transistor Optocoupler

FODM452, FODM453



MFP5 4.1X4.4, 2.54P
CASE 100AM

Description

The FODM452 and FODM453 optocouplers consist of an AlGaAs LED optically coupled to a high speed photo−detector transistor. The devices are housed in a compact 5−pin mini flat package for optimum mounting density.

The FODM453 features a high CMR rating for optimum common mode transient immunity.

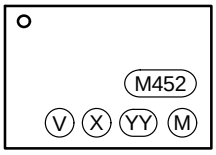
Features

- Compact 5−pin Mini Flat Package
- High Speed − 1 MBit/s
- Superior CMR − 15 kV/μs at V_{CM} = 1500 V (FODM453)
- Performance Guaranteed over Temperature (0 – 70°C)
- U.L. Recognized (File # E90700)
- VDE0884 Recognized (File # 136480)
  – Ordering Option V, e.g., FODM452V
- 260°C Reflow Capability for Pb−free Assembly
- These are Pb−Free Devices

Applications

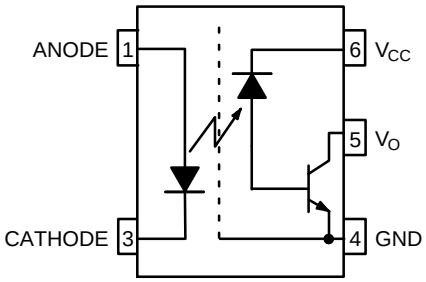
- Line Receivers
- Pulse Transformer Replacement
- Output Interface to CMOS−LSTTL−TTL
- Wide Bandwidth Analog Coupling

MARKING DIAGRAM



M45x = Device Number (x = 2, 3)
V = DIN EN/IEC60747−5−5 Mark (Note: Only Appears on Parts Ordered with VDE Option – See Order Entry Table)
X = One Digit Year Code, e.g., ‘7’
YY = ‘Two Digit Work Week Ranging from ‘01’ to ‘53’
M = Assembly Package Code

FUNCTIONAL SCHEMATIC



TRUTH TABLE

LED	Output
Off	High
On	Low

ORDERING INFORMATION

See detailed ordering and shipping information on page 10 of this data sheet.

PIN DEFINITIONS

Number	Name	Function Description
1	ANODE	Anode
3	CATHODE	Cathode
4	GND	Output Ground
5	V_O	Output Voltage
6	V_{CC}	Output Supply Voltage

SAFETY AND INSULATION RATINGS FOR MINI−FLAT PACKAGE (SO5 PIN)

(As per DIN EN/IEC60747−5−5. This optocoupler is suitable for “safe electrical insulation” only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.)

Symbol	Parameter	Min	Typ	Max	Unit
	Installation Classifications per DIN VDE 0110/1.89 Table 1	−	−	−	
	For Rated Main Voltage <150 Vrms	−	I−IV	−	
	For Rated Main Voltage <300 Vrms	−	I−III	−	
	Climatic Classification	−	40/85/21	−	
	Pollution Degree (DIN VDE 0110/1.89)	−	2	−	
CTI	Comparative Tracking Index	175	−	−	
V_{PR}	Input to Output Test Voltage, Method b, VIORM x 1.875 = V_{PR}, 100% Production Test with t_m = 1 s, Partial Discharge <5 pC	1060	−	−	
V_{PR}	Input to Output Test Voltage, Method a, VIORM x 1.5 = V_{PR}, Type and Sample Test with t_m = 60 s, Partial Discharge <5 pC	848	−	−	
V_{IORM}	Max Working Insulation Voltage	565	−	−	V_{peak}
V_{IOTM}	Highest Allowable Over Voltage	4000	−	−	V_{peak}
	External Creepage	5.0	−	−	mm
	External Clearance	5.0	−	−	mm
	Insulation thickness	0.5	−	−	mm
T_{Case}	Safety Limit Values, Maximum Values Allowed in the Event of a Failure, Case Temperature	150	−	−	°C
R_{IO}	Insulation Resistance at T_S, V_{IO} = 500 V	10^9	−	−	Ω

MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Rating	Unit
T_{STG}	Storage Temperature	−40 to +125	°C
T_{OPR}	Operating Temperature	−40 to +85	°C

EMITTER

I_F (avg)	DC/Average Forward Input Current	25	mA
I_F (pk)	Peak Forward Input Current (50% Duty Cycle, 1 ms P.W.)	50	mA
I_F (trans)	Peak Transient Input Current (≤1 μs P.W., 300 pps)	1.0	A
V_R	Reverse Input Voltage	5	V
P_D	Input Power Dissipation (No Derating Required over Specified Operating Temp Range)	45	mW

DETECTOR

I_O (avg)	Average Output Current	8	mA
I_O (pk)	Peak Output Current	16	mA
V_{CC}	Supply Voltage	−0.5 to 30	V
V_O	Output Voltage	−0.5 to 20	V
P_D	Output Power Dissipation (No Derating Required over Specified Operating Temp Range)	100	mW

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ELECTRICAL CHARACTERISTICS (T_A = 0 to 70°C unless otherwise noted)

Symbol	Parameter	Test Condition	Device	Min	Typ*	Max	Unit
INDIVIDUAL COMPONENT CHARACTERISTICS							
EMITTER							
V_F	Input Forward Voltage	I_F = 16 mA, T_A = 25°C		–	1.60	1.7	V
		I_F = 16 mA		–	–	1.8	
B_{VR}	Input Reverse Breakdown Voltage	I_R = 10 μA		5.0	–	–	V
$\Delta V_F/\Delta T_A$	Temperature Coefficient of Forward Voltage	I_F = 16 mA		–	−1.8	–	mV/°C
DETECTOR							
I_{OH}	Logic High Output Current	I_F = 0 mA, V_O = V_{CC} = 5.5 V, T_A = 25°C		–	.001	0.5	μA
		I_F = 0 mA, V_O = V_{CC} = 15 V, T_A = 25°C		–	.001	1	
		I_F = 0 mA, V_O = V_{CC} = 15 V		–	–	50	
I_{CCL}	Logic Low Supply Current	I_F = 16 mA, V_O = Open, V_{CC} = 15 V		–	100	200	μA
I_{CCH}	Logic high Supply Current	I_F = 0 mA, V_O = Open, V_{CC} = 15 V, T_A = 25°C		–	0.05	1	μA
		I_F = 0 mA, V_O = Open, V_{CC} = 15 V		–	–	2	
TRANSFER CHARACTERISTICS							
COUPLED							
CTR	Current Transfer Ratio (Note 1)	I_F = 16 mA, V_{CC} = 4.5 V; T_A = 25°C, V_{OL} = 0.4 V		20	–	50	%
		V_{OL} = 0.5 V		15	–	–	
V_{OL}	Logic LOW Output Voltage	I_F = 16 mA, I_O = 3 mA, V_{CC} = 4.5 V, T_A = 25°C		–	–	0.4	V
		I_F = 16 mA, I_O = 2.4 mA, V_{CC} = 4.5 V		–	–	0.5	
SWITCHING CHARACTERISTICS (V_{CC} = 5 V)							
T_{PHL}	Propagation Delay Time to Logic LOW	R_L = 1.9 kΩ, I_F = 16 mA, T_A = 25°C (Note 2) (Figure 9)		–	0.40	0.8	μs
		R_L = 1.9 kΩ, I_F = 16 mA (Note 2) (Figure 9)		–	–	1.0	μs
T_{PLH}	Propagation Delay Time to Logic HIGH	R_L = 1.9 kΩ, I_F = 16 mA, T_A = 25°C (Note 2) (Figure 9)		–	0.35	0.8	μs
		R_L = 1.9 kΩ, I_F = 16 mA (Note 2) (Figure 9)		–	–	1.0	μs
$\|CM_H\|$	Common Mode Transient Immunity at Logic HIGH	I_F = 0 mA, V_{CM} = 10 V_{P-P}, R_L = 1.9 kΩ, T_A = 25°C (Note 3) (Figure 10)	FODM452	5	15	–	KV/μs
		I_F = 0 mA, V_{CM} = 1500 V_{P-P}, R_L = 1.9 kΩ T_A = 25°C (Note 3) (Figure 10)	FODM453	15	40	–	KV/μs
$\|CM_L\|$	Common Mode Transient Immunity at Logic LOW	I_F = 16 mA, V_{CM} = 10 V_{P-P}, R_L = 1.9 kΩ, T_A = 25°C (Note 3) (Figure 10)	FODM452	5	15	–	KV/μs
		I_F = 16 mA, V_{CM} = 1500 V_{P-P}, R_L = 1.9 kΩ, T_A = 25°C (Note 3) (Figure 10)	FODM453	15	40	–	KV/μs
BW	Bandwidth	R_L = 100 Ω		–	3	–	MHz
ISOLATION CHARACTERISTICS							
V_{ISO}	Withstand Insulation Test Voltage	RH ≤ 50%, T_A = 25°C, t = 1 min. (Note 4)		3750	–	–	V_{RMS}
C_{I-O}	Capacitance (Input to Output)	f = 1 MHz (Note 4)		–	0.2	–	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

*All Typicals at T_A = 25°C

1. Current Transfer Ratio is defined as a ratio of output collector current, I_O, to the forward LED input current, I_F, times 100%.
2. The 1.9 kΩ load represents 1 TTL unit load of 1.6 mA and 5.6 kΩ pull−up resistor.
3. Common mode transient immunity in logic high level is the maximum tolerable (positive) dV_{cm}/dt on the leading edge of the common mode pulse signal V_{CM}, to assure that the output will remain in a logic high state (i.e., V_O > 2.0 V). Common mode transient immunity in logic low level is the maximum tolerable (negative) dV_{cm}/dt on the trailing edge of the common mode pulse signal, V_{CM}, to assure that the output will remain in a logic low state (i.e., V_O < 0.8 V).
4. Device is considered a two terminal device: Pins 1, and 3 are shorted together and Pins 4, 5, and 6 are shorted together.

TYPICAL PERFORMANCE CURVES

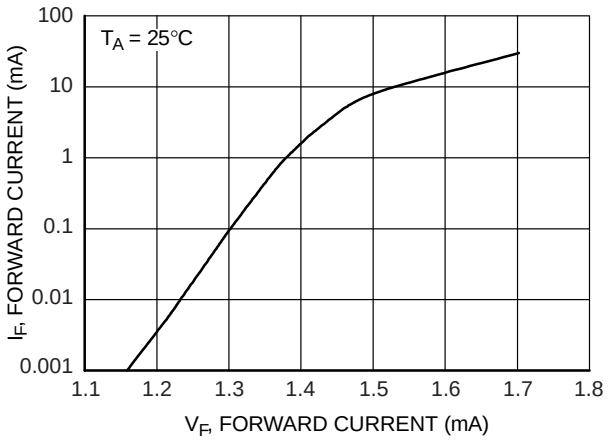


Figure 1. Input Forward Current vs Forward Voltage

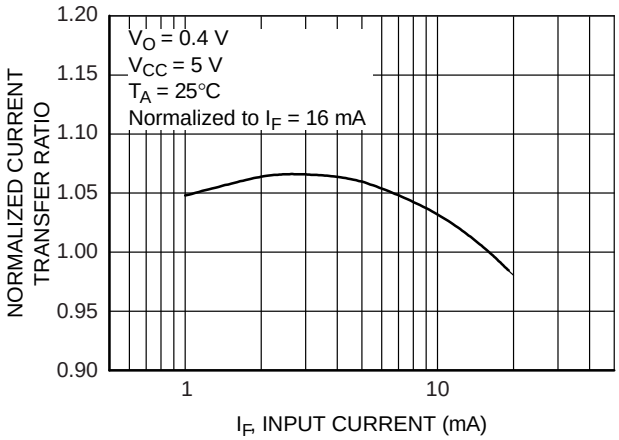


Figure 2. Normalized Current Transfer Ratio vs. Input Current

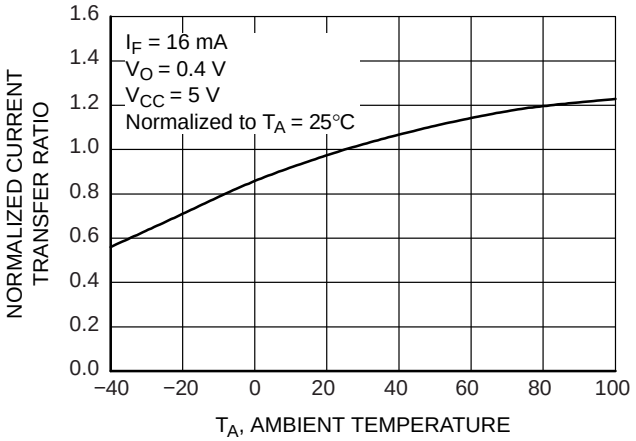


Figure 3. Normalized Current Transfer Ratio vs. Ambient Temperature

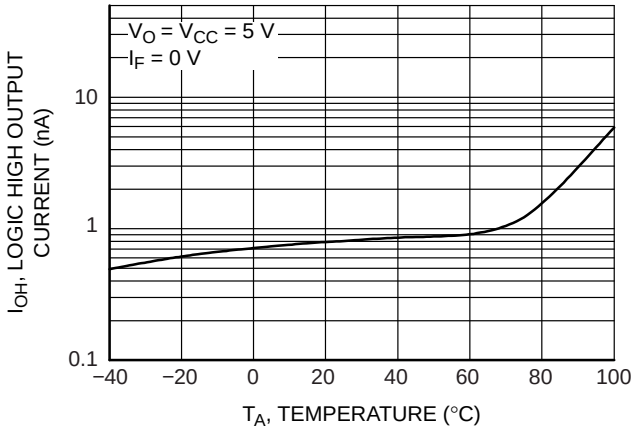


Figure 4. Logic High Output Current vs. Ambient Temperature

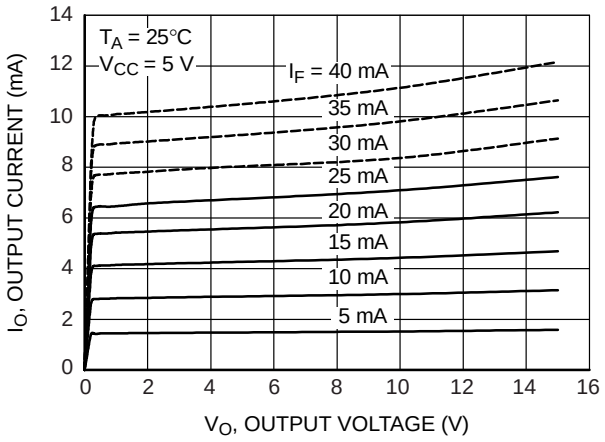


Figure 5. DC and Pulsed Transfer Characteristics

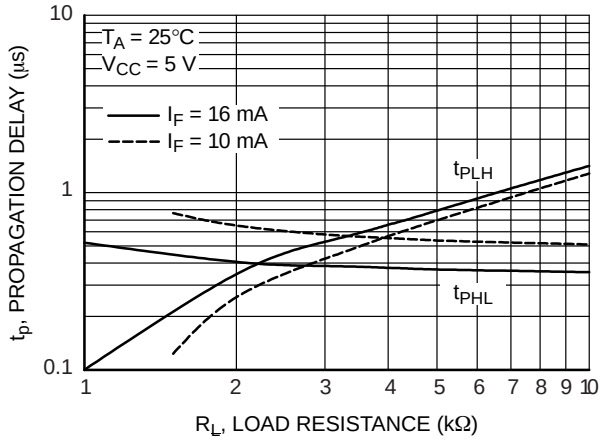


Figure 6. Propagation Delay vs. Load Resistance

TYPICAL PERFORMANCE CURVES (Continued)

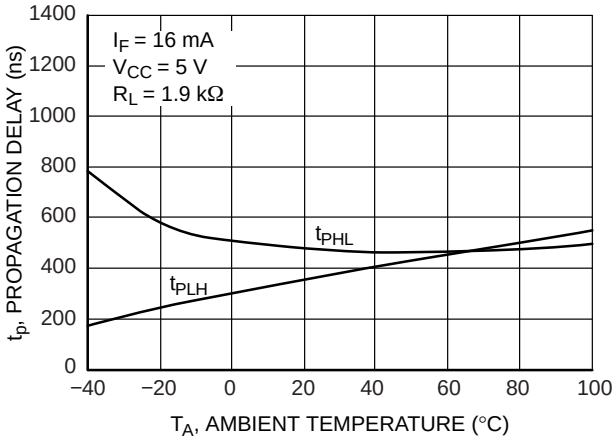


Figure 7. Propagation Delay vs. Ambient Temperature

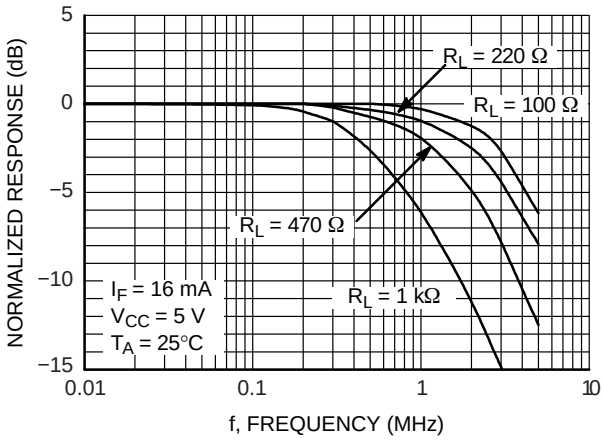


Figure 8. Frequency Response

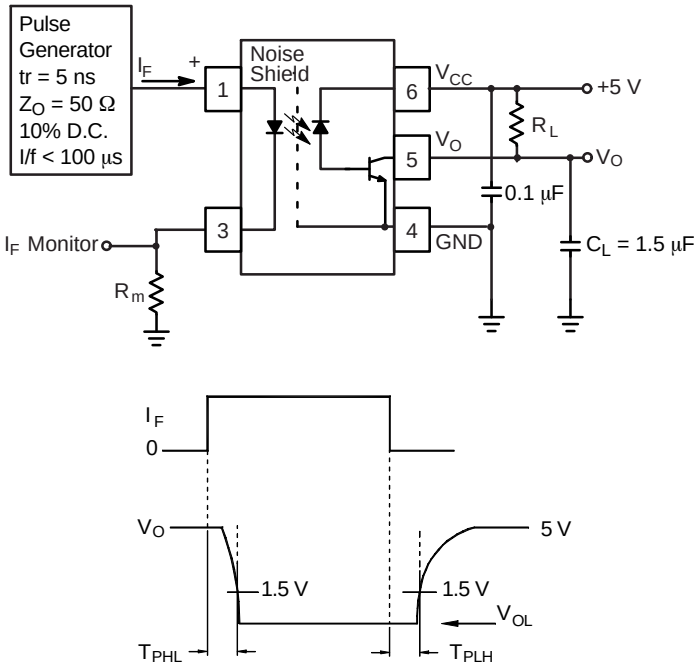


Figure 9. Switching Time Test Circuit

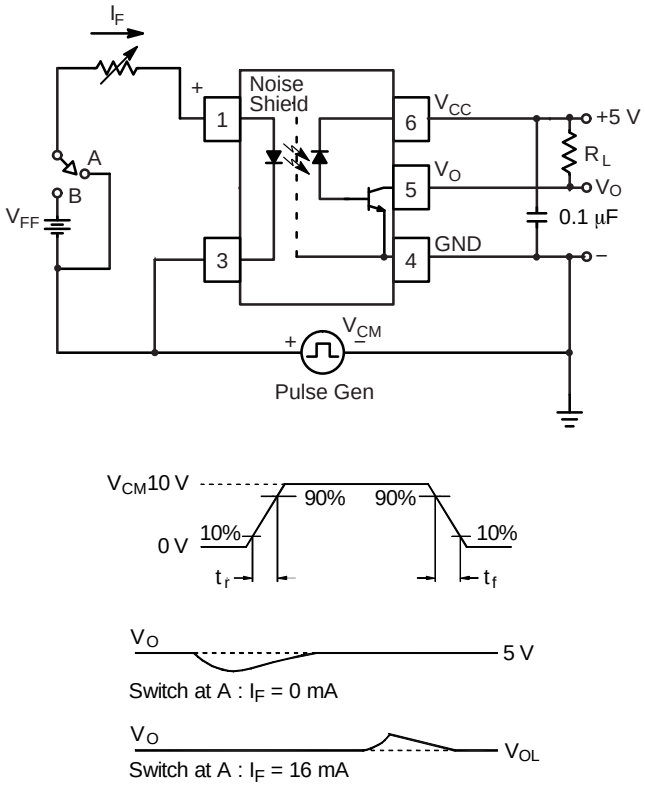


Figure 10. Common Mode Immunity Test Circuit

FOOTPRINT DRAWING FOR PCB LAYOUT

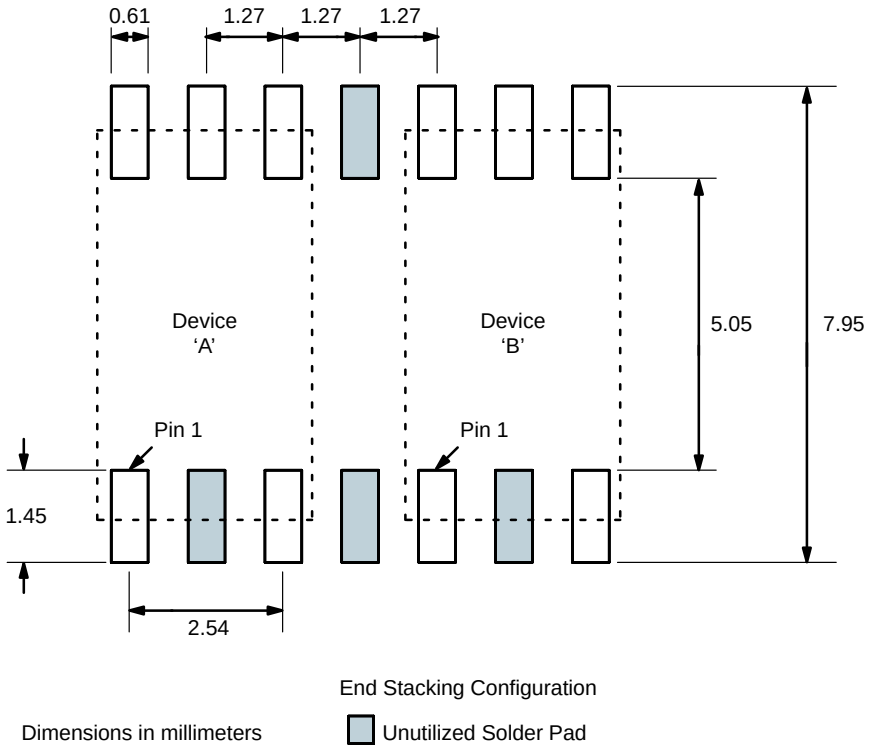


Figure 11. Footprint Drawing for PCB Layout

REFLOW PROFILE

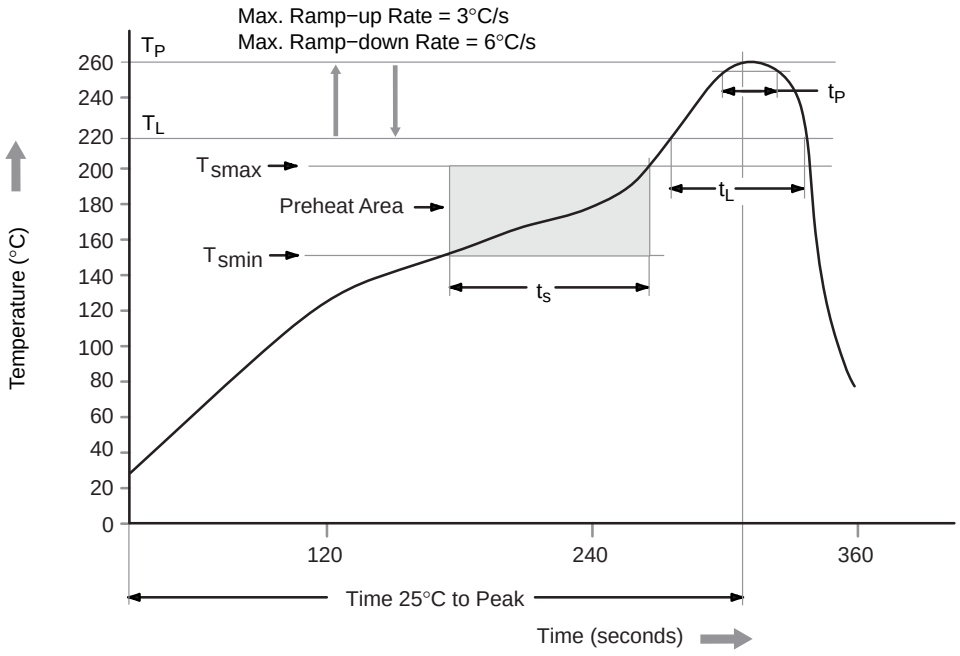


Figure 12. Reflow Profile

Table 1. REFLOW PROFILE

Profile Feature	Pb−Free Assembly Profile
Temperature Minimum (T_{smin})	150°C
Temperature Maximum (T_{smax})	200°C
Time (t_S) from (T_{smin} to T_{smax})	60 – 120 seconds
Ramp−up Rate (t_L to t_P)	3°C/second max.
Liquidous Temperature (T_L)	217°C
Time (t_L) Maintained Above (T_L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / –5°C
Time (t_P) within 5°C of 260°C	30 seconds
Ramp−down Rate (T_P to T_L)	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

ORDERING INFORMATION

Part Number	Package	Shipping†
FODM452	MFP5 4.1X4.4, 2.54P (Pb−Free)	100 Units / Tube
FODM452R2	MFP5 4.1X4.4, 2.54P (Pb−Free)	2500 / Tape & Reel
FODM452V	MFP5 4.1X4.4, 2.54P IEC60747−5−2 (Pb−Free)	100 Units / Tube
FODM452R2V	MFP5 4.1X4.4, 2.54P IEC60747−5−2 (Pb−Free)	2500 / Tape & Reel
FODM453	MFP5 4.1X4.4, 2.54P (Pb−Free)	100 Units / Tube
FODM453R2	MFP5 4.1X4.4, 2.54P (Pb−Free)	2500 / Tape & Reel
FODM453V	MFP5 4.1X4.4, 2.54P IEC60747−5−2 (Pb−Free)	100 Units / Tube
FODM453R2V	MFP5 4.1X4.4, 2.54P IEC60747−5−2 (Pb−Free)	2500 / Tape & Reel

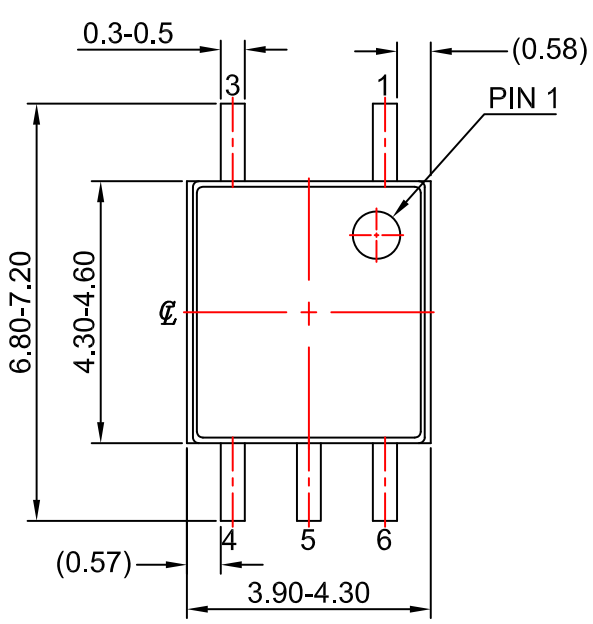
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

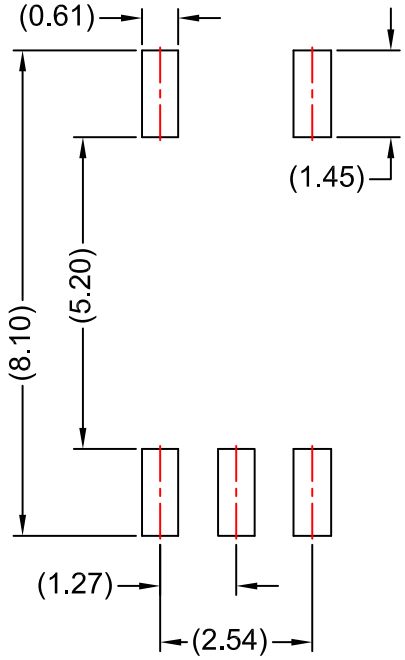
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

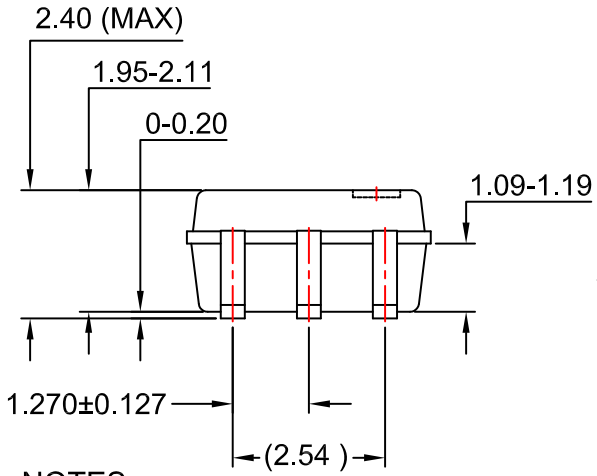
MFP5 4.1X4.4, 2.54P
CASE 100AM
ISSUE O

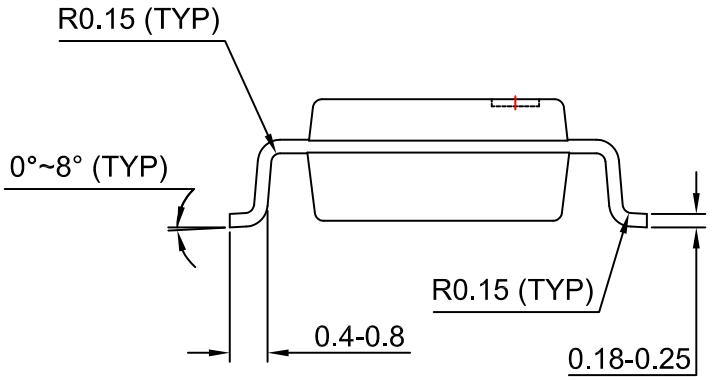
DATE 31 AUG 2016





LAND PATTERN RECOMMENDATION





NOTES:

A) NO STANDARD APPLIES TO THIS PACKAGE

B) ALL DIMENSIONS ARE IN MILLIMETERS.

C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION

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DESCRIPTION:	**MFP5 4.1X4.4, 2.54P**	**PAGE 1 OF 1**

ADDITIONAL INFORMATION

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